

1. 適用範圍 / SCOPE

此份規格書涵蓋 MHTC 金屬板電流感測電阻元件相關規格.

This specification covers MHTC, which are Metal Strap Current Sensing Resistor.

2. 產品型號/TYPE NUMBER

MHTC	0805	M	xWx	Rxxx	*
(1)		(2)	(3)	(4)	(5)

- (1) 產品系列號 / SERIES NUMBER : Ex.MHTC0805 = 短電極/ Short electrode ; 兩端子 / two terminal ; 無側導 / without side electrode / size "0.05x0.08"
- (2) 產品材質 / Material : M = 錳銅合金 / MnCu alloy
- (3) 產品瓦特數 / Power Rating : Ex. 1W0=1.0 Watt
- (4) 產品阻值 / Nominal Resistance Value : Ex. 2mΩ →R002
- (5) 元件電阻偏差值 / Resistance Tolerance : Ex. F=±1% ; G=±2%
- (6) 產品碼/Product code:Ex. S→Special design ; blank→Original design

3. 產品尺寸 / PRODUCT DIMENSIONS

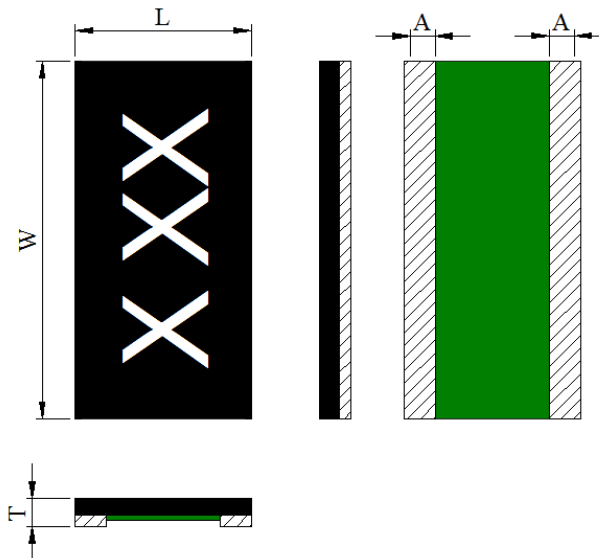


圖 1 / Fig.1

Unit(mm)

Part Number	W	L	T	A
MHTC0805M1W0-series R001	2.00±0.25	1.25±0.25	0.40±0.15	0.38±0.20
MHTC0805M1W0-series 1M50~R005	2.00±0.25	1.25±0.25	0.40±0.15	0.32±0.20

4. 產品結構及使用材料說明(參考圖 2) / STRUCTURE & MATERIAL (Ref to Fig.2)

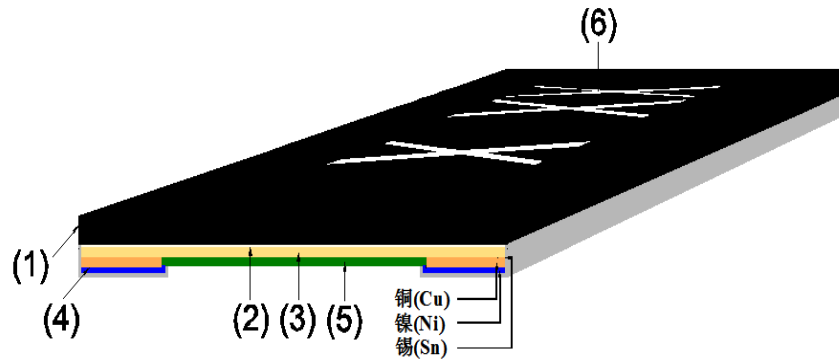


圖 2 / Fig.2

4.1 基板 / Substrate(1) : 環氧樹脂 / epoxy

4.2 粘著膠層/Adhesive(2): 環氧樹脂 / epoxy

4.3 電阻本體 / Resistive element(3) : M = 錳銅合金 / MnCu alloy

4.4 端電極 / Terminal electrode(4) : 錫、鎳、銅 / Sn、Ni、Cu

4.5 保護防焊層 / Protective coating(5) : 防火級環氧樹脂,符合 UL- 94-V0 要求(綠色) /
Flame-retardant epoxy, meets UL- 94-V0 requirements (green)

4.6 文印防焊層 / Marking coating(6) : 防火級環氧樹脂,符合 UL- 94-V0 要求(白色) /
Flame-retardant epoxy, meets UL- 94-V0 requirements (white)

5. 電氣特性 / ELECTRICAL CHARACTERISTICS

Part Number	Resistance Value (mΩ)	Power Rating (Watt)	Resistance Tolerance (%)	TCR (ppm/°C)
MHTC0805M1W0-series R001~1M50	1~1.5	1.0	±1%(F)	±150
MHTC0805M1W0-series R002~R005	2~5	1.0	±1%(F)	±100

6. 產品特性及信賴性測試規範 / PRODUCT CHARACTERISTICS AND RELIABILITY TEST STANDARD

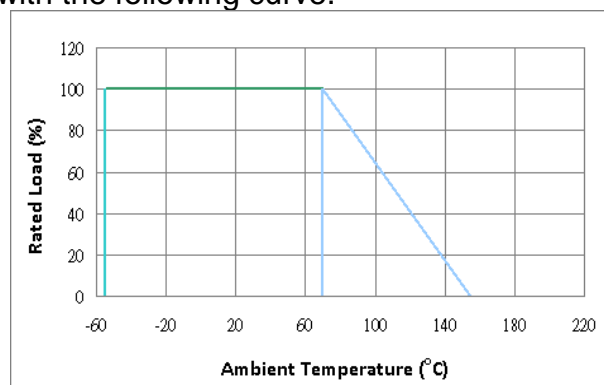
測試方法 Parameter	條件 Conditions	允收標準 Requirements
瞬間過載測試 / Short Time Over Load	$P = 2.5P_r$; $T = 25 \pm 2^\circ\text{C}$, $t = 5\text{sec.}$	$\pm(1.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.13
高溫測試 / High Temp. Exposure	$T = +155 \pm 2^\circ\text{C}$; $t = 1000\text{h}$	$\pm(1.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.25
低溫測試 / Low Temp. Storage	$T = -55 \pm 2^\circ\text{C}$; $t = 1000\text{h}$	$\pm(1.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.25
濕度負載壽命測試 / Moisture Load Life (60°C、95%RH)	$V_{\text{test}} = V_{\text{max}}$; $T = 60 \pm 2^\circ\text{C}$; $\text{RH} = 95\%$; $t = 90\text{min ON}$, 30min OFF , 1000h	$\pm(2.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.25
冷熱衝擊測試 / Thermal Shock	$[-55^\circ\text{C } 30\text{min.} \rightarrow \text{R.T. } 3\text{min.} \rightarrow +155^\circ\text{C } 30\text{min.}$ $\rightarrow \text{R.T. } 3\text{min.}]$, 100 個連續循環 / 100Cycles	$\pm(1.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.19
在 70°C 下負載壽命測試 / Load Life at 70°C	$V_{\text{test}} = V_{\text{max}}$; $T = 70 \pm 2^\circ\text{C}$; $t = 90\text{min ON}$, 30min OFF , 1000h	$\pm(2.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.25
可焊性測試 / Solderability	浸入錫爐 / Dip into solder at $T = 245 \pm 5^\circ\text{C}$, $t = 3 \pm 0.5\text{sec.}$	錫涵蓋面積 / The covered area >95% IEC60115-1 4.17
抗焊熱性測試 / Resistance to Solder Heat	經熱風式迴焊爐 / Through Reflow $T = 275 \pm 5^\circ\text{C}$, $t = 20 \pm 1\text{sec.}$	$\pm(1.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.18
機械衝擊測試 / Mechanical Shock	加速度 $a = 100\text{G}$, 振幅時間 $t = 11\text{ms}$, 5 個衝擊 $a = 100\text{G}$, $t = 11\text{ms}$, 5 times shock	$\pm(1.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.21
基板彎曲測試 / Substrate Bending	兩支撐點間距 / Span between fulcrums : 90mm ; 振幅 / Bend Width: 2mm ; 測試板 / Testboard: 玻璃纖維板 / Glass Epoxy Board ; 厚度 / Thickness = 1.6mm	$\pm(1.0\% + 0.5\text{m}\Omega)$ IEC60115-1 4.33

7. 環境特性 / ENVIRONMENTAL CHARACTERISTIC
7-1 操作溫度範圍: $-55^\circ\text{C} \sim 155^\circ\text{C}$ / Operating Temperature: $-55^\circ\text{C} \sim 155^\circ\text{C}$
額定功率溫度衰變曲線 / Typical Thermal Derating Curve

額定功率乃指於 70°C 以內可連續滿額功率使用的術語。

下圖為當操作溫度高於 70°C 時的可使用功率衰減曲線。

Power rating is based on continuous full load operation at rated ambient temperature of 70°C . For resistors operated at ambient temp. in excess of 70°C , the max. load shall be derated in accordance with the following curve.



7-2 存儲條件 / STORAGE CONDITIONS

在溫度+10°C~40°C、相對濕度 $\leq 75\%$ 的密閉條件下可存放2年。 /

Under airtight in temperature+10°C~40°C、relative humidity $\leq 75\%$ can store 2 years.

在溫度+10°C~60°C、相對濕度為95%的非露天下最多可存放30天。 /

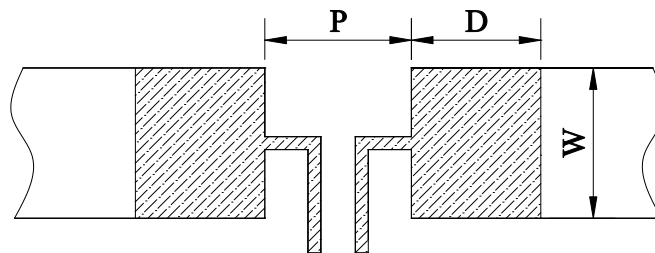
Without dew in temperature+10°C~60°C、relative humidity be 95% maximum value for 30days.

8. 焊錫墊尺寸及焊接條件 / SOLDER PAD SIZE AND WELDING CONDITIONS

8-1 建議如下圖焊接方式焊接，並滿足所要求的尺寸。 / Propose that the following picture installation way is installed, and satisfied the required size.

Part Number	P	W	D	Loading
MHTC0805M1W0-series R001	0.40mm	2.30mm	0.90mm	1.0w
MHTC0805M1W0-series 1M50~R005	0.50mm	2.30mm	0.85mm	1.0w

loading : 適用於本司建議焊墊設計並使用於限定穩定電流下 /
suit for specific pad layout and specific steady current



8-2 建議客戶焊接參數 / Recommended Customer Soldering Parameters

8-2-1 回流焊溫度曲線 / Solder reflow Temperature condition (圖 3 / Fig.3)

預熱段 / Preheating : 145 ± 15°C, max.120 sec.

焊錫段 / Soldering : min. 220°C, max. 60 sec.

允許最高溫度 / Maximum temperature : 260±5°C, max. 10sec.

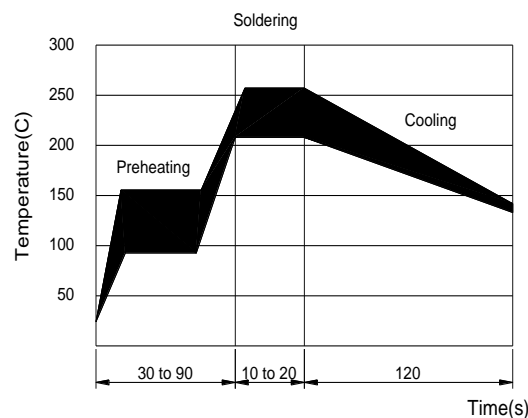


圖 3 / Fig.3

8-2-2 允許烙鐵焊接條件(熱風設備) / Rework temperature (hot air equipment) : 350°C,
3~5seconds

8-2-3 焊接方法建議 / Recommended reflow methods

焊接熱源方式可用紅外線, 熱蒸氣, 熱風. / IR, vapor phase oven, hot air oven
如果焊錫溫度超過允許最高溫度, 則產品本身會有功能損壞的疑慮. / If reflow temperatures
exceed the recommended profile, devices may not meet the performance requirements.

9. 批量生產後出貨測試項目 / Lot ACCEPTANCE TEST REQUIREMENTS

每一批生產均須作入庫檢驗, 每一批生產單量不可超過500Kpcs. /

Qualification shall consist of passing a program of following tests. Parts shall be pulled from
each lot and maximum lot quantity shall be within 500Kpcs.

9-1 外觀 / Visual

方法 / Procedure : 利用放大鏡進行檢查 / Visual

標準 / Acceptance Criteria : 不能有髒污、不潔、文印錯誤、破損等 / No parts are outstandingly
stained

9-2 尺寸 / Dimensions

方法 / Procedure : 使用合適且經校正的尺規 / As appropriate, calipers, micrometers,
optical comparator, or approved gages

標準 / Acceptance Criteria : 尺寸均在規定標準範圍內 / No parts outside specific dimensions

9-3 單體元件電阻(Ro) / Resistance (Ro)

方法 / Procedure : 在 25°C 下利用四線量測技術量測之 / Resistance shall be measured with 25
°C in the 4-wire resistance test

標準 / Acceptance Criteria : 電阻值均在規定標準範圍內 / The resistance of the test device shall
be within the limits specified

9-4 電阻溫度係數 / TCR

方法 / Procedure : 利用四線法量測出元件分別在 25°C 及125°C 下的電阻值, 並將其帶入下面公
式中即可得出 TCR值 / Getting the sampling device resistance values measured in 25°C and
125°C and put them in to the following equation to calculate the TCR

標準 / Acceptance Criteria : 溫度係數值均在規定標準範圍內 / All parts must within the specific
 $TCR = (R_b - R_a) / R_a \times 1 / (T_b - T_a) \times 10^6$

9-5 絕緣電阻 / Insulation resistance (Ri)

方法 / Procedure : 利用絕緣測試儀量測 / Resistance between protective layer and resistive shall
be measured by high ohm meter

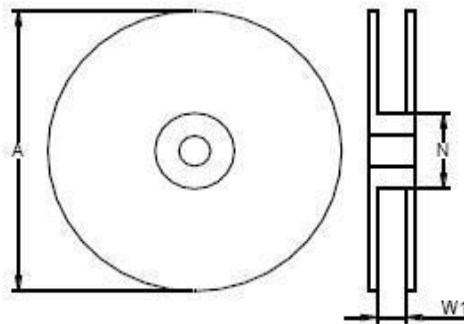
標準 / Acceptance Criteria : 防焊層與電阻本體絕緣電阻至少高於100MΩ / The resistance of the
test device shall over 100MΩ

10. 包裝訊息 / PACKAGING INFORMATION

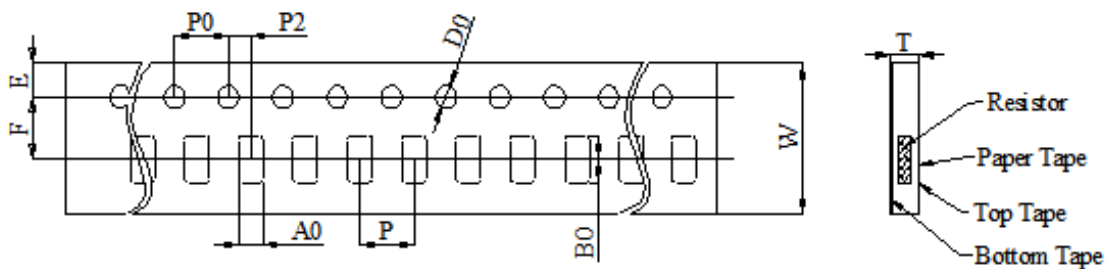
10-1 包裝數量、重量 / QUANTITY & WEIGHT

型號 / Type Number	數量 / Quantity (pcs)	重量 / Weight (g)
MHTC0805M1W0-series	5,000	120±30

10-2 捲輪規格 / Reel & Tape specifications



型號 / Type Number	A ± 5 (mm)	N ± 2 (mm)	W1 ± 1 (mm)
MHTC0805M1W0-series	178	60	9.0



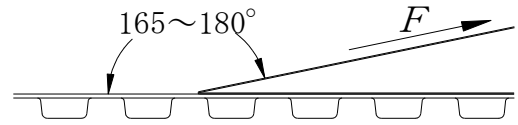
Unit(mm)

MHTC0805M1W0-series							
W	8.00 ± 0.30	P0	4.00 ± 0.10	P	4.00 ± 0.10	P2	2.00 ± 0.10
A0	1.45 ± 0.10	B0	2.20 ± 0.10	D0	1.50 ± 0.10	F	3.50 ± 0.10
E	1.75 ± 0.10	T	0.60 ± 0.10	/	/	/	/

10-3 密封膠膜剝離強度要求 / Peeling Strength of Seal Tape

F = 剝離強度 : 0.1 – 1.0N (10 - 100gf)

F = Peeling Strength: 0.1 – 1.0N (10 - 100gf)



11. 其他 / OTHERS

11-1 如果在使用中有超出本規格書的要求，必須經由雙方協商確認。 / In the event that an impropriety is found beyond this specification , it shall be fixed by mutual agreement between the parties.

11-2 如果本規格書有不適當的情況，必須通過雙方協商並由本公司修改。 / In the event that an impropriety is found in this specification , Juneway Electronic Technology Co., Ltd. shall amend it by mutual agreement between the parties.

单击下面可查看定价，库存，交付和生命周期等信息

[>>Walter\(华德\)](#)